

Title (en)

Method and assembly for heating a metal circuit board

Title (de)

Verfahren und Anordnung zum Erwärmen einer Metallplatine

Title (fr)

Procédé et agencement destinés à chauffer une platine de métal

Publication

EP 2570204 B1 20181031 (DE)

Application

EP 12181241 A 20120821

Priority

DE 102011053672 A 20110916

Abstract (en)

[origin: EP2570204A2] The method involves positioning the heating units (6,11) of a heating device (1), between a lower contact element (5) and an upper contact element (9). The receiving portions (4,8) are integrated with the contact elements (5,9) and made of highly heat conductive material having a conductivity of 150 W/mK. A metal circuit board (2) is positioned between the contact elements, and heated under a pressure for a period of less than 120 seconds, in a heating phase to a temperature of 200-450[deg] . An independent claim is included for arrangement for heating a metal circuit board.

IPC 8 full level

B21D 22/02 (2006.01); **B21D 37/16** (2006.01); **C21D 1/34** (2006.01); **C21D 9/46** (2006.01)

CPC (source: EP US)

B21D 22/022 (2013.01 - EP US); **B21D 37/16** (2013.01 - EP US); **C21D 1/34** (2013.01 - EP US); **C21D 9/46** (2013.01 - EP US)

Cited by

US11131001B2; WO2017025632A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DE 102011053672 B4 20170810; US 2013068756 A1 20130321

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